



PRODUCT CHANGE NOTICE**PCN-2560 REV 1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
16 December, 2021	16 March, 2022	Discrete	Wafer FAB Source and Assembly & Test Site	2560
TITLE				
Additional Wafer Source (GFAB) and Additional Assembly and Test Site (SAT)				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified an additional internal wafer source located in Greenock, Scotland (GFAB) and an additional internal assembly and test site (SAT) in Shanghai, China for select products listed below.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
IMPACT				
No change in datasheet parameters and product performance				
PRODUCTS AFFECTED				
Table 1: Additional wafer source (GFAB) Table 2: Additional wafer source (GFAB) and assembly and test site (SAT) Table 3: Additional wafer source (GFAB) and assembly mold compound change				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Additional Wafer Source (GFAB)

SDM01U50CP3-7	SDM05U20CSP-7	SDM1A40CSP-7	SDM1U30CP3-7	SDM2U20CSP-7	SDM2U40CSP-7B
SDM02L30CP3-7	SDM05U20S3-7	SDM1L20DCP3-7	SDM1U40CSP-7	SDM2U20SD3-7	SDM4A30EP3-7B
SDM02M30DCP3-7	SDM05U40CSP-7	SDM1L30CSP-7	SDM2A20CSP-7	SDM2U30CSP-7	SDM4A40EP3-7B
SDM02U30CSP-7	SDM1A30CSP-7	SDM1U20CSP-7	SDM2A40CSP-7B	SDM2U30CSP-7B	SDM5U45EP3-7
SDM05A30CP3-7	SDM1A40CP3-7				

Table 2 - Additional Wafer Source (GFAB) and Assembly and Test Site (SAT)

SDT20100CTB-13	SDT60100CTB-13				
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Table 3 - Additional Wafer Source (GFAB) and Assembly Mold Compound Change

SDT5A100SAF-13	SDT5A100SB-13	SDT5H100SB-13			
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